

Surface mount high linearity silicon NPN RF bipolar transistor









Product description

The BFP640 is a RF bipolar transistor based on SiGe:C technology that is part of Infineon's established sixth generation transistor family. Its transition frequency $f_{\rm T}$ of 42 GHz and high linearity characteristics at low currents make this device particularly suitable for energy efficiency designs at frequency as high as 8 GHz. It remains cost competitive without compromising on ease of use.



Feature list

- Minimum noise figure NF_{min} = 0.65 dB at 1.9 GHz, 3 V, 6 mA
- High gain G_{ma} = 24 dB at 1.9 GHz, 3 V, 25 mA
- OIP₃ = 26.5 dBm at 1.9 GHz, 3 V, 25 mA

Product validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Potential applications

- Low noise amplifiers (LNAs) in GNSS receivers
- LNAs in satellite radio (SDARs, DAB) receivers
- LNAs in multimedia applications such as CATV and FM radio

Device information

Table 1 Part information

| Product name / Ordering code | Package | Pin co | nfigura | tion | | Marking | Pieces / Reel |
|------------------------------|---------|--------|---------|-------|-------|---------|---------------|
| BFP640 / BFP640H6327XTSA1 | SOT343 | 1 = B | 2 = E | 3 = C | 4 = E | R4s | 3000 |

Attention: ESD (Electrostatic discharge) sensitive device, observe handling precautions

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Absolute maximum ratings

1 Absolute maximum ratings

Table 2 Absolute maximum ratings at $T_A = 25$ °C (unless otherwise specified)

| Parameter | Symbol | Va | lues | Unit | Note or test condition | |
|----------------------------|------------------|------|------|------|------------------------------------|--|
| | | Min. | Max. | | | |
| Collector emitter voltage | V_{CEO} | _ | 4.1 | ٧ | Open base | |
| | | | 3.6 | | T _A = -55 °C, open base | |
| Collector emitter voltage | V _{CES} | | 13 | | E-B short circuited | |
| Collector base voltage | V_{CBO} | | 13 | | Open emitter | |
| Emitter base voltage | V_{EBO} | | 1.2 | | Open collector | |
| Base current | I _B | | 3 | mA | - | |
| Collector current | Ic | | 50 | | | |
| Total power dissipation 1) | P _{tot} | | 200 | mW | <i>T</i> _S ≤ 90 °C | |
| Junction temperature | TJ | | 150 | °C | - | |
| Storage temperature | T_{Stg} | -55 | | | | |

Attention: Stresses above the max. values listed here may cause permanent damage to the device.

Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding only one of these values may cause irreversible damage to the integrated circuit.

 T_S is the soldering point temperature. T_S is measured on the emitter lead at the soldering point of the PCB.



Thermal characteristics

2 Thermal characteristics

Table 3 Thermal resistance

| Parameter | Symbol | Values | | | Unit | Note or test condition |
|----------------------------|-------------------|--------|------|------|------|------------------------|
| | | Min. | Тур. | Max. | | |
| Junction - soldering point | R _{thJS} | _ | 300 | _ | K/W | - |

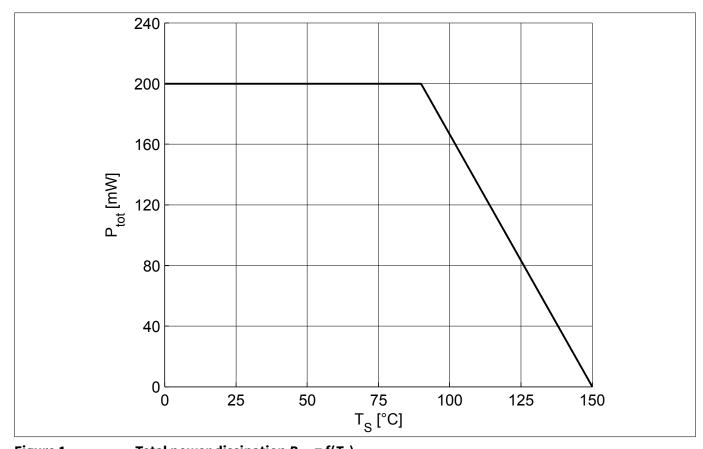


Figure 1 Total power dissipation $P_{\text{tot}} = f(T_S)$

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Electrical characteristics

3 Electrical characteristics

3.1 DC characteristics

Table 4 DC characteristics at $T_A = 25$ °C

| Parameter | Symbol | Values | | | Unit | Note or test condition |
|--|----------------------|--------|------|-------------------|------|--|
| | | Min. | Тур. | Max. | | |
| Collector emitter breakdown voltage | V _{(BR)CEO} | 4.1 | 4.7 | _ | V | $I_C = 1 \text{ mA}, I_B = 0,$ open base |
| Collector emitter leakage current I _{CES} | I _{CES} | - | 1 | 400 ²⁾ | nA | $V_{CE} = 13 \text{ V}, V_{BE} = 0,$ E-B short circuited |
| | | | 1 | 40 ²⁾ | | $V_{CE} = 5 \text{ V}, V_{BE} = 0,$ E-B short circuited |
| Collector base leakage current | I _{CBO} | | 1 | 40 ²⁾ | | $V_{\text{CB}} = 5 \text{ V}, I_{\text{E}} = 0,$ open emitter |
| Emitter base leakage current | I _{EBO} | | 1 | 40 ²⁾ | | $V_{\text{EB}} = 0.5 \text{ V}, I_{\text{C}} = 0,$ open collector |
| DC current gain | h _{FE} | 110 | 180 | 270 | | $V_{CE} = 3 \text{ V}, I_{C} = 30 \text{ mA},$ pulse measured |

3.2 General AC characteristics

Table 5 General AC characteristics at $T_A = 25 \,^{\circ}\text{C}$

| Parameter | Symbol | | Values | | | Note or test condition | |
|-------------------------------|-----------------|------|--------|------|-----|--|--|
| | | Min. | Тур. | Max. | | | |
| Transition frequency | f_{T} | - | 42 | _ | GHz | $V_{CE} = 3 \text{ V}, I_{C} = 30 \text{ mA},$ f = 2 GHz | |
| Collector base capacitance | C _{CB} | | 0.08 | | pF | $V_{\text{CB}} = 3 \text{ V}, V_{\text{BE}} = 0,$ f = 1 MHz, emitter grounded | |
| Collector emitter capacitance | C _{CE} | | 0.24 | | | $V_{CE} = 3 \text{ V}, V_{BE} = 0,$ f = 1 MHz, base grounded | |
| Emitter base capacitance | C _{EB} | | 0.51 | | | $V_{\text{EB}} = 0.5 \text{ V}, V_{\text{CB}} = 0,$ f = 1 MHz, collector grounded | |

² Maximum values not limited by the device but by the short cycle time of the 100% test.



3.3 Frequency dependent AC characteristics

Measurement setup is a test fixture with Bias-T's in a 50 Ω system, $T_{\rm A}$ = 25 °C.

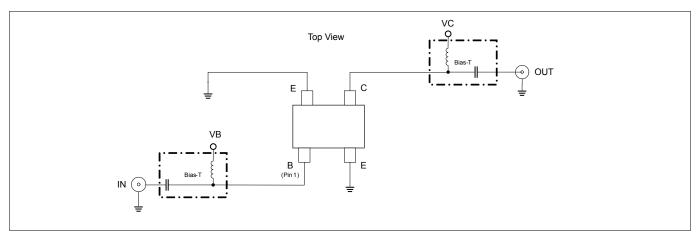


Figure 2 Testing circuit

Table 6 AC characteristics, $V_{CE} = 3 \text{ V}, f = 450 \text{ MHz}$

| Parameter | Symbol | Values | | | Unit | Note or test condition |
|---|-------------------|--------|------|------|------|--|
| | | Min. | Тур. | Max. | | |
| Power gain | | - | | _ | dB | |
| Maximum power gain | G _{ms} | | 33 | | | $I_{\rm C} = 25 {\rm mA}$ |
| Transducer gain | $ S_{21} ^2$ | | 31.5 | | | |
| Noise figure | | | | | | |
| Minimum noise figure | NF _{min} | | 0.55 | | | $I_{\rm C}$ = 6 mA |
| Associated gain | G _{ass} | | 26 | | | |
| Linearity | | | | | dBm | |
| 3rd order intercept point at output | OIP ₃ | | 23.5 | | | $I_{\rm C} = 25 \text{ mA}, Z_{\rm S} = Z_{\rm L} = 50 \Omega$ |
| • 1 dB gain compression point at output | OP _{1dB} | | 10.5 | | | |

Table 7 AC characteristics, $V_{CE} = 3 \text{ V}, f = 900 \text{ MHz}$

| Parameter | Symbol | Values | | | Unit | Note or test condition |
|--|-------------------|--------|------|------|------|---|
| | | Min. | Тур. | Max. | | |
| Power gain | | _ | | _ | dB | |
| Maximum power gain | G _{ms} | | 29 | | | $I_{\rm C} = 25 {\rm mA}$ |
| Transducer gain | $ S_{21} ^2$ | | 27.5 | | | |
| Noise figure | | | | | | |
| Minimum noise figure | NF _{min} | | 0.6 | | | $I_{\rm C}$ = 6 mA |
| Associated gain | G _{ass} | | 24 | | | |
| Linearity | | | | | dBm | |
| 3rd order intercept point at output | OIP ₃ | | 25.5 | | | $I_{\rm C} = 25 \text{mA}, Z_{\rm S} = Z_{\rm L} = 50 \Omega$ |
| • 1 dB gain compression point at output | OP _{1dB} | | 12 | | | |

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Table 8 AC characteristics, $V_{CE} = 3 \text{ V}, f = 1.5 \text{ GHz}$

| Parameter | Symbol | Values | | | Unit | Note or test condition |
|---|-------------------|--------|------|------|------|--|
| | | Min. | Тур. | Max. | | |
| Power gain | | _ | | _ | dB | |
| Maximum power gain | G _{ms} | | 25.5 | | | $I_{\rm C} = 25 {\rm mA}$ |
| Transducer gain | $ S_{21} ^2$ | | 23.5 | | | |
| Noise figure | | | | | | |
| Minimum noise figure | NF _{min} | | 0.6 | | | $I_{\rm C}$ = 6 mA |
| Associated gain | G _{ass} | | 21 | | | |
| Linearity | | | | | dBm | |
| 3rd order intercept point at output | OIP ₃ | | 25.5 | | | $I_{\rm C} = 25 {\rm mA}, Z_{\rm S} = Z_{\rm L} = 50 {\rm \Omega}$ |
| 1 dB gain compression point at output | OP _{1dB} | | 11.5 | | | |

Table 9 AC characteristics, $V_{CE} = 3 \text{ V}, f = 1.9 \text{ GHz}$

| Parameter | Symbol | Values | | | Unit | Note or test condition |
|---|--------------------------|--------|------|------|------|--|
| | | Min. | Тур. | Max. | | |
| Power gain | | _ | | _ | dB | |
| Maximum power gain | G _{ms} | | 24 | | | $I_{\rm C} = 25 {\rm mA}$ |
| Transducer gain | $ S_{21} ^2$ | | 21.5 | | | |
| Noise figure | | | | | | |
| Minimum noise figure | <i>NF</i> _{min} | | 0.65 | | | $I_{\rm C} = 6 \text{mA}$ |
| Associated gain | G _{ass} | | 19.5 | | | |
| Linearity | | | | | dBm | |
| 3rd order intercept point at output | OIP ₃ | | 26.5 | | | $I_{\rm C} = 25 \text{ mA}, Z_{\rm S} = Z_{\rm L} = 50 \Omega$ |
| • 1 dB gain compression point at output | OP _{1dB} | | 12.5 | | | |

Table 10 AC characteristics, $V_{CE} = 3 \text{ V}$, f = 2.4 GHz

| Parameter | Symbol | | Values | | Values Unit | | Unit | Note or test condition |
|--|-------------------|------|--------|------|-------------|---|------|------------------------|
| | | Min. | Тур. | Max. | | | | |
| Power gain | | _ | | _ | dB | | | |
| Maximum power gain | G _{ms} | | 22 | | | $I_{\rm C} = 25 {\rm mA}$ | | |
| Transducer gain | $ S_{21} ^2$ | | 19.5 | | | | | |
| Noise figure | | | | | | | | |
| Minimum noise figure | NF _{min} | | 0.7 | | | $I_{\rm C} = 6 \text{mA}$ | | |
| Associated gain | G _{ass} | | 18 | | | | | |
| Linearity | | | | | dBm | | | |
| 3rd order intercept point at output | OIP ₃ | | 27.5 | | | $I_{\rm C} = 25 \text{mA}, Z_{\rm S} = Z_{\rm L} = 50 \Omega$ | | |
| $\bullet \hspace{0.5cm} 1 dB gain compression point at output$ | OP _{1dB} | | 12 | | | | | |

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Electrical characteristics

AC characteristics, $V_{CE} = 3 \text{ V}$, f = 3.5 GHzTable 11

| Parameter | Symbol | Values | | Values Unit | | Note or test condition |
|---|--------------------------|--------|------|-------------|-----|---|
| | | Min. | Тур. | Max. | | |
| Power gain | | _ | | _ | dB | |
| Maximum power gain | G _{ma} | | 18 | | | $I_{\rm C} = 25 {\rm mA}$ |
| Transducer gain | $ S_{21} ^2$ | | 16.5 | | | |
| Noise figure | | | | | | |
| Minimum noise figure | <i>NF</i> _{min} | | 0.85 | | | $I_{\rm C}$ = 6 mA |
| Associated gain | G _{ass} | | 15 | | | |
| Linearity | | | | | dBm | |
| 3rd order intercept point at output | OIP ₃ | | 27.5 | | | $I_{\rm C} = 25 \text{mA}, Z_{\rm S} = Z_{\rm L} = 50 \Omega$ |
| • 1 dB gain compression point at output | OP _{1dB} | | 12 | | | |

AC characteristics, $V_{CE} = 3 \text{ V}$, f = 5.5 GHzTable 12

| Parameter | Symbol | Values | | | Unit | Note or test condition |
|--|-------------------|--------|------|------|------|---|
| | | Min. | Тур. | Мах. | | |
| Power gain | | _ | | _ | dB | |
| Maximum power gain | G _{ma} | | 14 | | | $I_{\rm C} = 25 {\rm mA}$ |
| Transducer gain | $ S_{21} ^2$ | | 12.5 | | | |
| Noise figure | | | | | | |
| Minimum noise figure | NF _{min} | | 1.1 | | | $I_{\rm C}$ = 6 mA |
| Associated gain | G _{ass} | | 12 | | | |
| Linearity | | | | | dBm | |
| 3rd order intercept point at output | OIP ₃ | | 27.5 | | | $I_{\rm C} = 25 \text{mA}, Z_{\rm S} = Z_{\rm L} = 50 \Omega$ |
| • 1 dB gain compression point at output | OP _{1dB} | | 12.5 | | | |

Note:

 $G_{\rm ms}$ = $IS_{21}/S_{12}I$ for k < 1; $G_{\rm ma}$ = $IS_{21}/S_{12}I$ (k-(k^2 -1) $^{1/2}$) for k > 1. In order to get the NF_{min} values stated in this chapter, the test fixture losses have been subtracted from all measured results. OIP₃ value depends on termination of all intermodulation frequency components. Termination used for this measurement is 50 Ω from 0.2 MHz to 12 GHz.



3.4 Characteristic DC diagrams

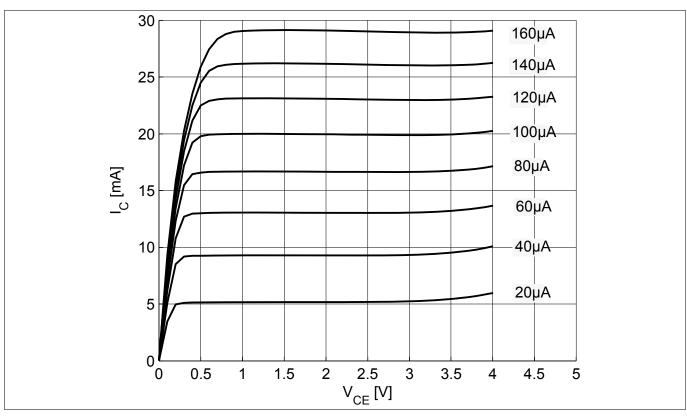


Figure 3 Collector current vs. collector emitter voltage $I_C = f(V_{CE})$, $I_B = parameter$

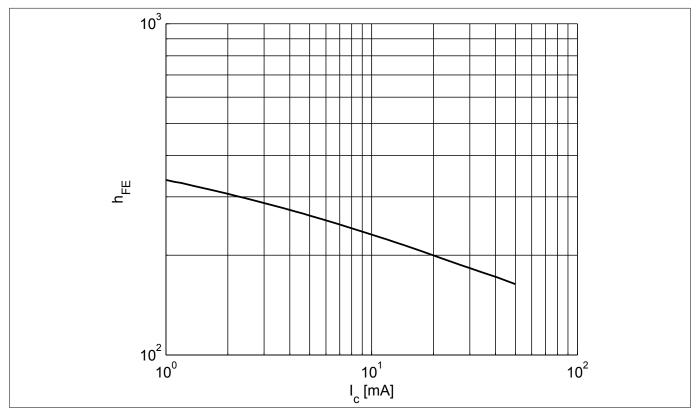


Figure 4 DC current gain $h_{FE} = f(I_C)$, $V_{CE} = 3 \text{ V}$



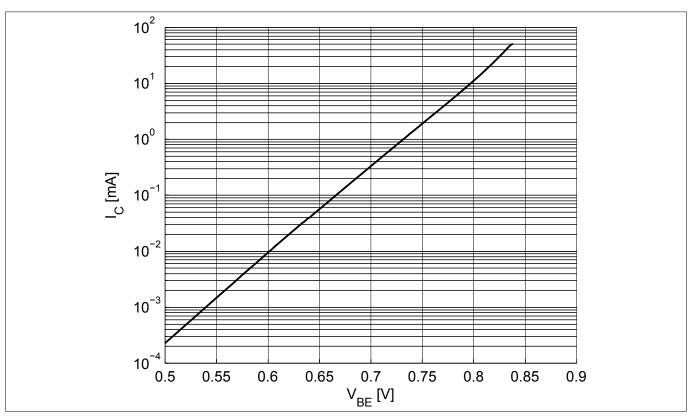


Figure 5 Collector current vs. base emitter forward voltage $I_C = f(V_{BE})$, $V_{CE} = 2 \text{ V}$

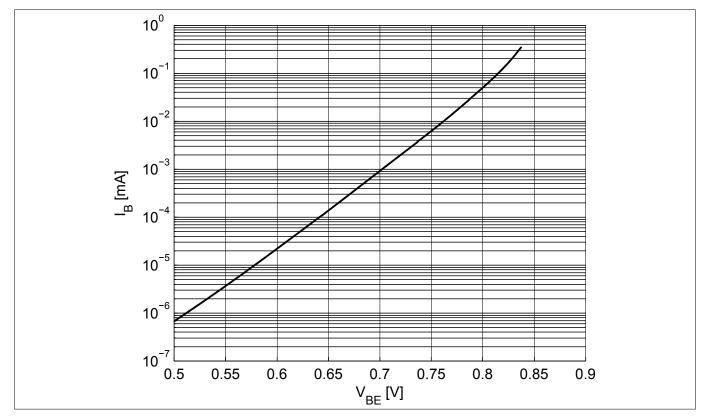


Figure 6 Base current vs. base emitter forward voltage $I_B = f(V_{BE})$, $V_{CE} = 2 \text{ V}$

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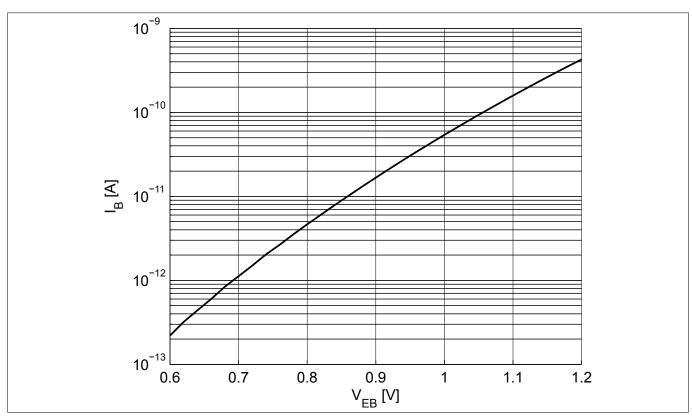


Figure 7 Base current vs. base emitter reverse voltage $I_B = f(V_{EB})$, $V_{CE} = 2 \text{ V}$



3.5 Characteristic AC diagrams

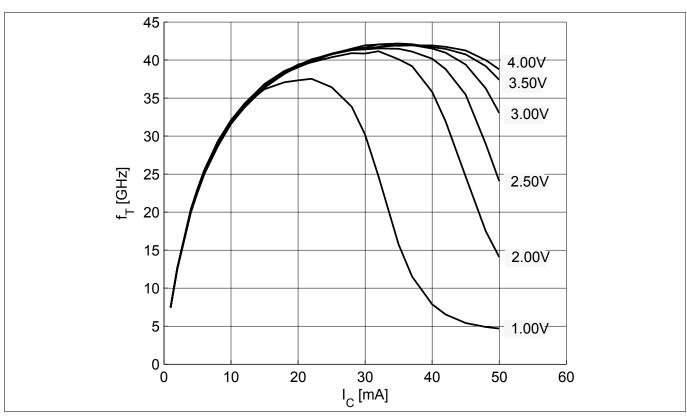


Figure 8 Transition frequency $f_T = f(I_C)$, f = 2 GHz, $V_{CE} =$ parameter

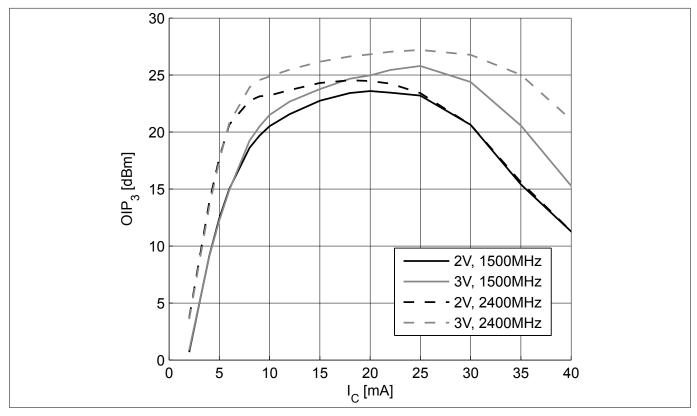


Figure 9 3rd order intercept point $OIP_3 = f(I_C)$, $Z_S = Z_L = 50 \Omega$, V_{CE} , f = parameters



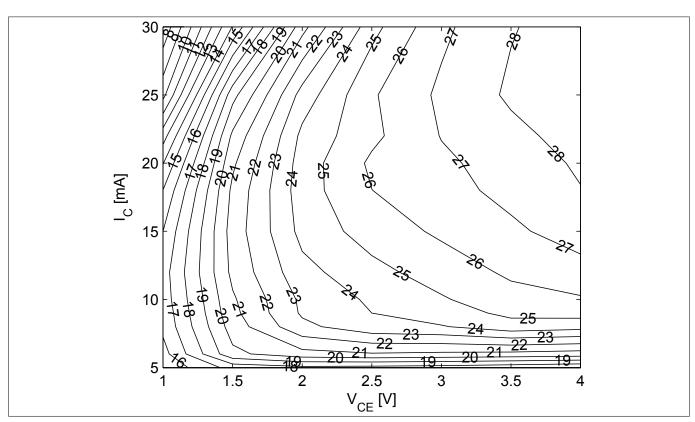
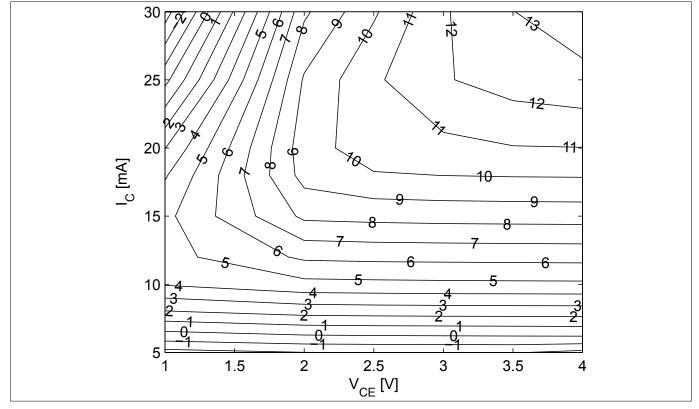


Figure 10 3rd order intercept point at output OIP_3 [dBm] = $f(I_C, V_{CE}), Z_S = Z_L = 50 \Omega, f = 2.4 \text{ GHz}$



Compression point at output OP_{1dB} [dBm] = $f(I_C, V_{CE})$, $Z_S = Z_L = 50 \Omega$, f = 2.4 GHzFigure 11

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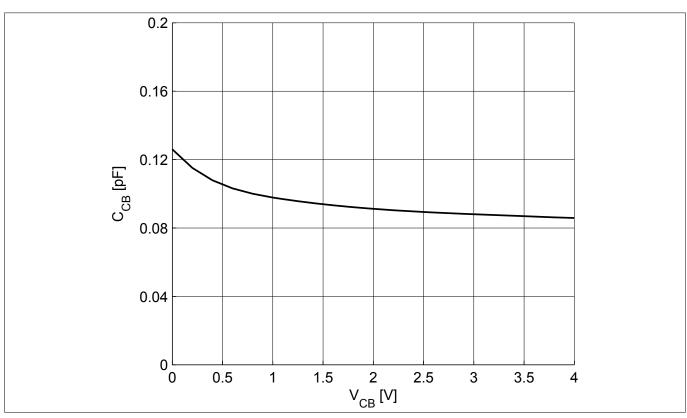


Figure 12 Collector base capacitance $C_{CB} = f(V_{CB}), f = 1 \text{ MHz}$

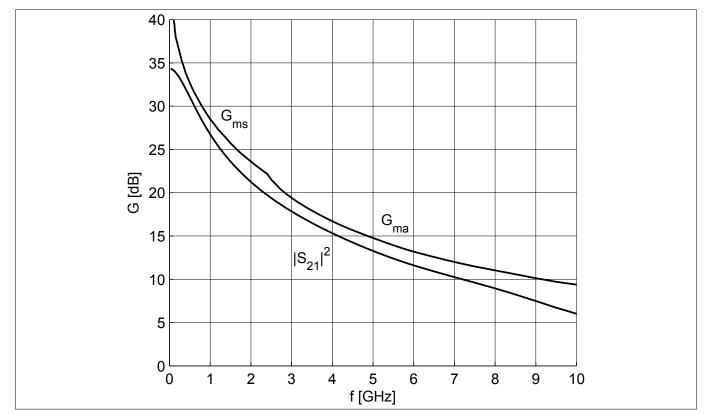


Figure 13 Gain G_{ma} , G_{ms} , $IS_{21}I^2 = f(f)$, $V_{CE} = 3 \text{ V}$, $I_C = 25 \text{ mA}$

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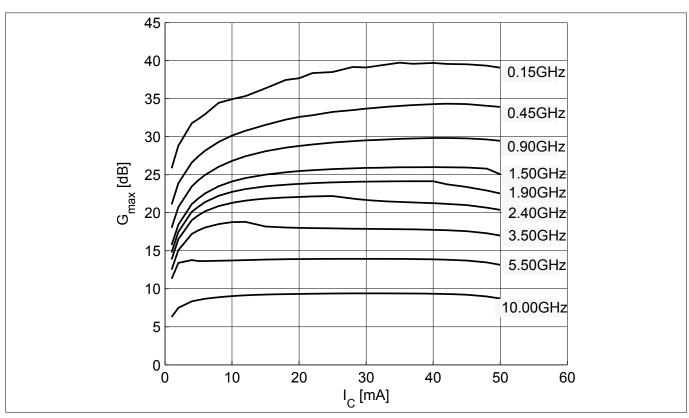


Figure 14 Maximum power gain $G_{\text{max}} = f(I_{\text{C}})$, $V_{\text{CE}} = 3 \text{ V}$, f = parameter in GHz

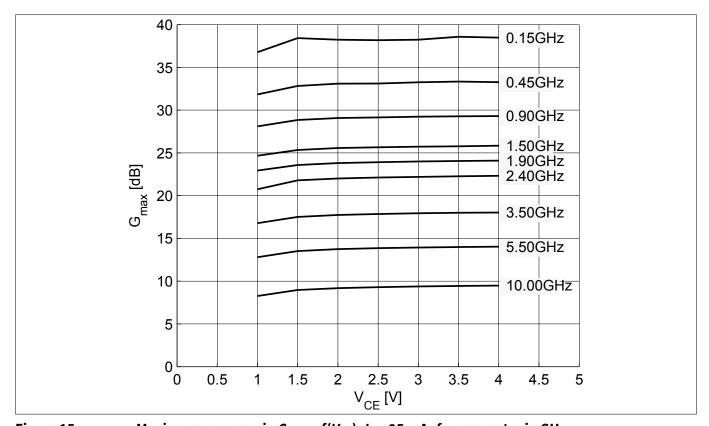


Figure 15 Maximum power gain $G_{\text{max}} = f(V_{\text{CE}})$, $I_{\text{C}} = 25 \text{ mA}$, f = parameter in GHz



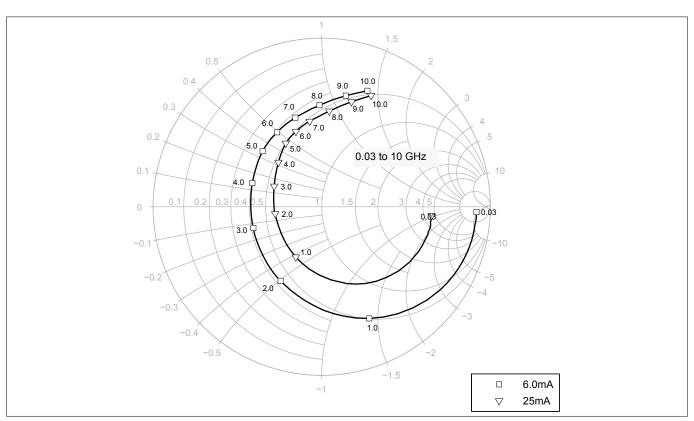


Figure 16 Input reflection coefficient $S_{11} = f(f)$, $V_{CE} = 3 \text{ V}$, $I_C = 6 / 25 \text{ mA}$

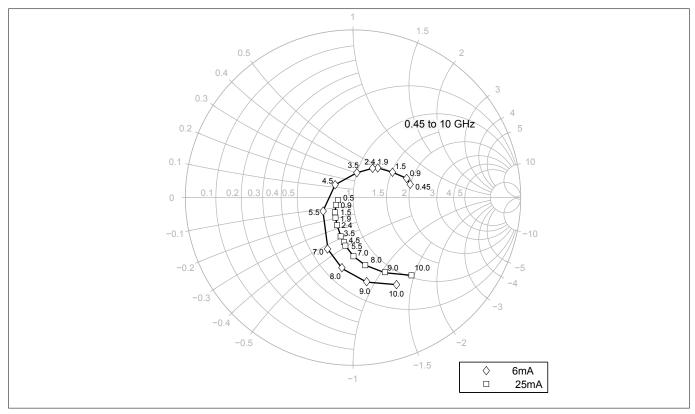


Figure 17 Source impedance for minimum noise figure $Z_{S,opt} = f(f)$, $V_{CE} = 3 \text{ V}$, $I_C = 6 / 25 \text{ mA}$



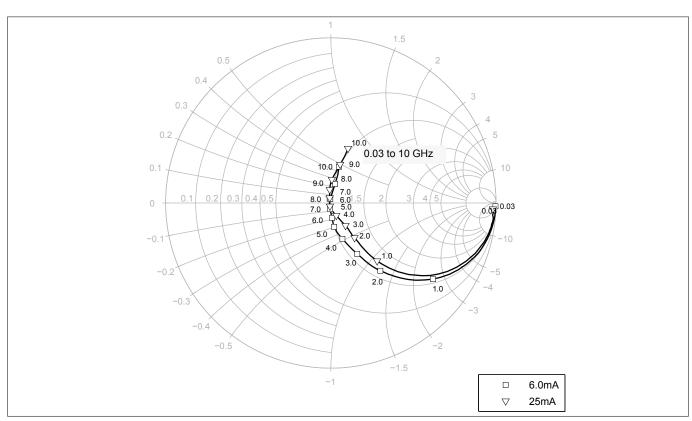


Figure 18 Output reflection coefficient $S_{22} = f(f)$, $V_{CE} = 3 \text{ V}$, $I_C = 6 / 25 \text{ mA}$

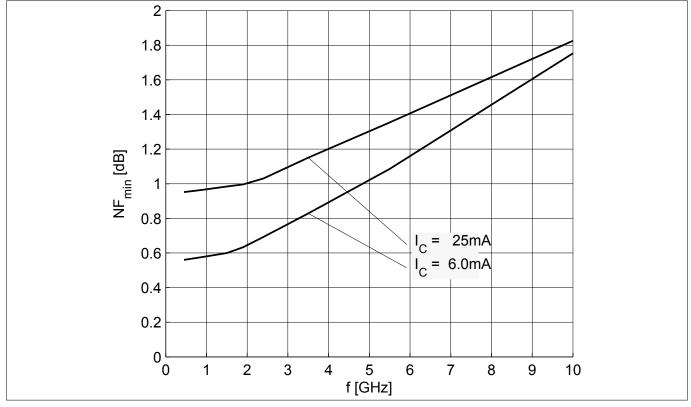


Figure 19 Noise figure $NF_{min} = f(f)$, $Z_S = Z_{S,opt}$, $V_{CE} = 3 \text{ V}$, $I_C = 6 / 25 \text{ mA}$



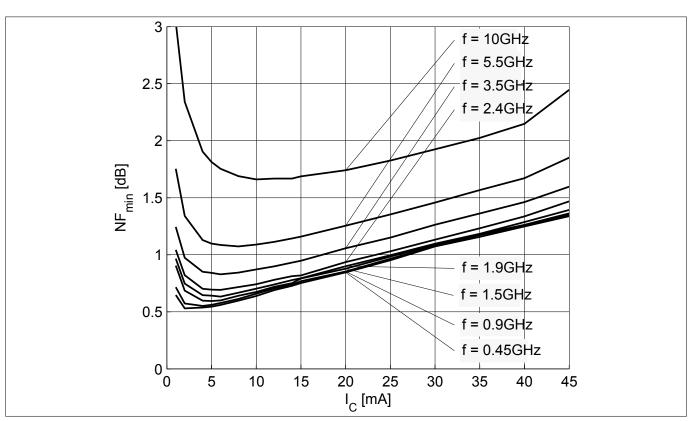


Figure 20 Noise figure $NF_{min} = f(I_C)$, $Z_S = Z_{S,opt}$, $V_{CE} = 3 \text{ V}$, f = parameter in GHz

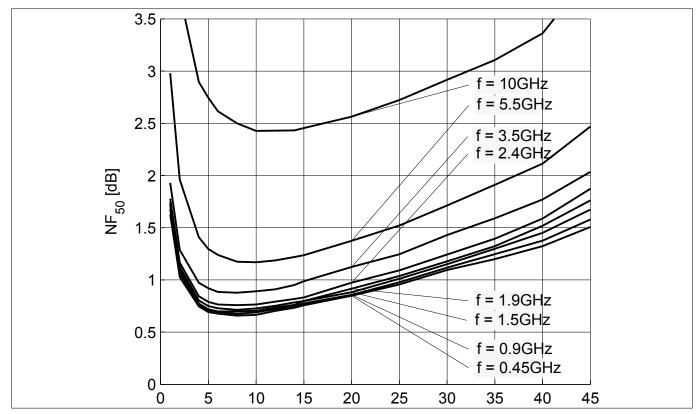


Figure 21 Noise figure $NF_{50} = f(I_C)$, $Z_S = 50 \Omega$, $V_{CE} = 3 V$, f = parameter in GHz

Note: The curves shown in this chapter have been generated using typical devices but shall not be considered as a guarantee that all devices have identical characteristic curves. $T_A = 25 \,^{\circ}\text{C}$.



Package information SOT343

4 Package information SOT343

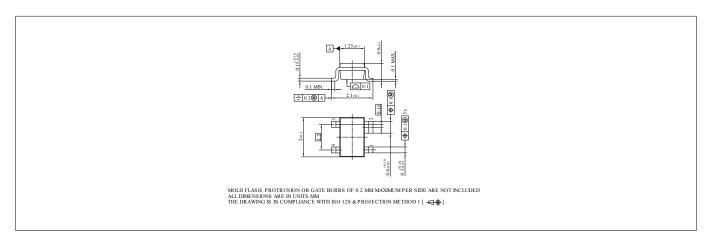


Figure 22 Package outline

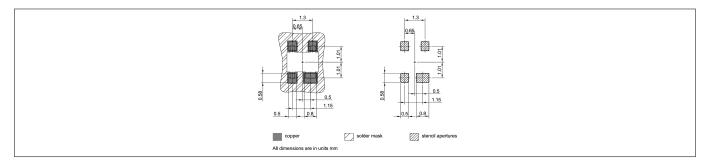


Figure 23 Foot print

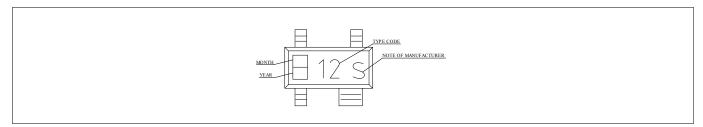


Figure 24 Marking layout example

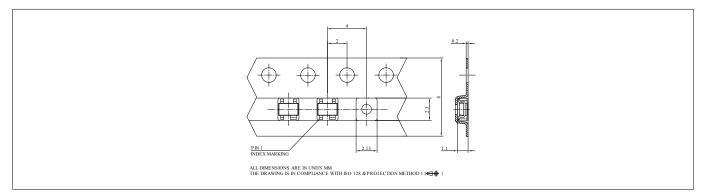


Figure 25 Tape dimensions

Surface mount high linearity silicon NPN RF bipolar transistor



Revision history

Revision history

| Document version | Date of release | Description of changes |
|------------------|-----------------|------------------------|
| Revision 3.0 | 2019-01-25 | New datasheet layout. |

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